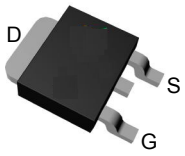
Features

- 30V/30A,
  $R_{DS(ON)}$=15mΩ (typ.) @ V_{GS}=10V
  $R_{DS(ON)}$=22mΩ (typ.) @ V_{GS}=4.5V
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

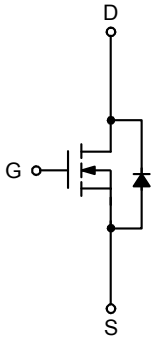
Applications

- Power Management in Desktop Computer or DC/DC Converters.

Pin Description



Top View of TO-252-2



N-Channel MOSFET

Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings (T_A=25°C Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		±20	
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	
I_S	Diode Continuous Forward Current	T_C=25°C	30	A
I_D	Continuous Drain Current	T_C=25°C	30	
		T_C=100°C	22	
I_{DM} [a]	Pulsed Drain Current	T_C=25°C	90	
P_D	Maximum Power Dissipation	T_C=25°C	35.7	W
		T_C=100°C	14.3	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	3.5	°C/W
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	t ≤ 10s	17	°C/W
		Steady State	40	
I_{AS} [b]	Avalanche Current, Single pulse (L=0.1mH)		19	A
E_{AS} [b]	Avalanche Energy, Single pulse (L=0.1mH)		18	mJ

Note a: Pulse width limited by maximum junction temperature.
Note b: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_j=25°C).

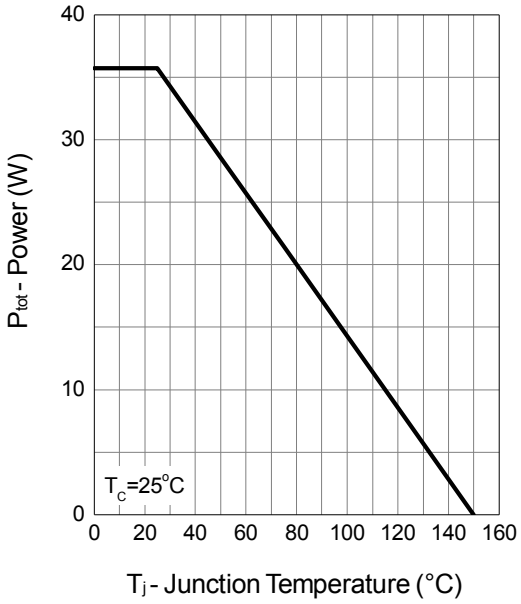
Electrical Characteristics (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250μA	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=24V, V_{GS}=0V	-	-	1	μA
		T_J=85°C	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA	1	1.7	2	V
I_{GSS}	Gate Leakage Current	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$ [c]	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=20A	-	15	18	mΩ
		T_J=125°C	-	20	-	
		V_{GS}=4.5V, I_{DS}=10A	-	22	26	
Gfs	Forward Transconductance	V_{DS}=5V , I_D=15A	-	24	-	S
Diode Characteristics						
V_{SD} [c]	Diode Forward Voltage	I_{SD}=5A, V_{GS}=0V	-	0.79	1.1	V
t_{rr}	Reverse Recovery Time	I_F=20A, dI_{SD}/dt=100A/μs	-	6	-	ns
t_a	Charge Time		-	5	-	
t_b	Discharge Time		-	11	-	
Q_{rr}	Reverse Recovery Charge		-	4.8	-	nC
Dynamic Characteristics [d]						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz	1.5	2.3	3.5	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, Frequency=1.0MHz	700	870	1045	pF
C_{oss}	Output Capacitance		96	120	145	
C_{rss}	Reverse Transfer Capacitance		60	76	91	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=15V, R_L=15Ω, I_{DS}=1A, V_{GEN}=10V, R_G=1Ω	-	12	-	ns
t_r	Turn-on Rise Time		-	11.8	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	23.2	-	
t_f	Turn-off Fall Time		-	4.4	-	
Gate Charge Characteristics [d]						
Q_g	Total Gate Charge	V_{DS}=15V, V_{GS}=10V, I_{DS}=20A	-	16	20	nC
Q_g	Total Gate Charge	V_{DS}=15V, V_{GS}=4.5V, I_{DS}=20A	-	7.2	-	
Q_{gth}	Threshold Gate Charge		-	1.48	-	
Q_{gs}	Gate-Source Charge		-	3	-	
Q_{gd}	Gate-Drain Charge		-	2.7	-	

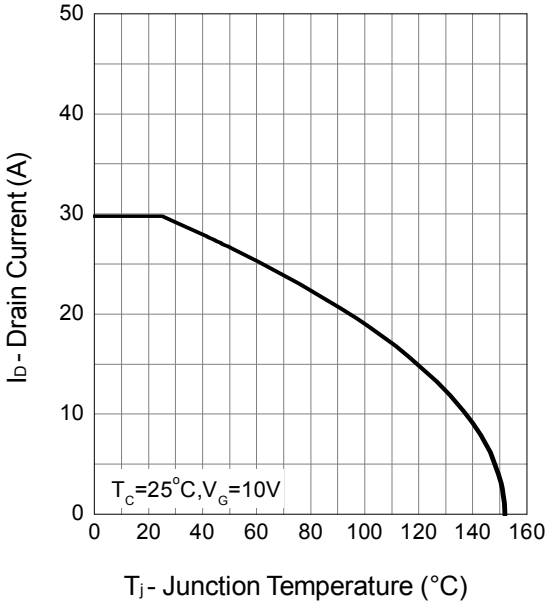
Note c: Pulse test ; pulse width≤300μs, duty cycle≤2%.
Note d: Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

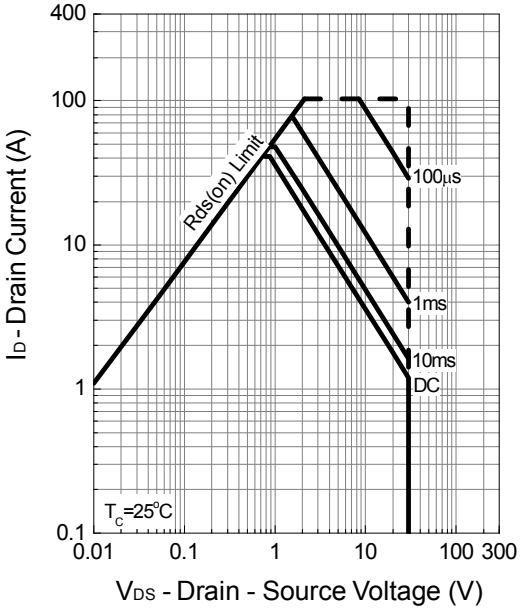
Power Dissipation



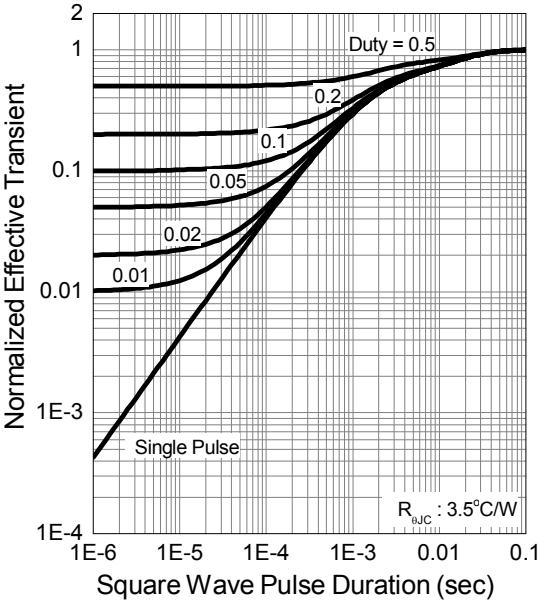
Drain Current



Safe Operation Area

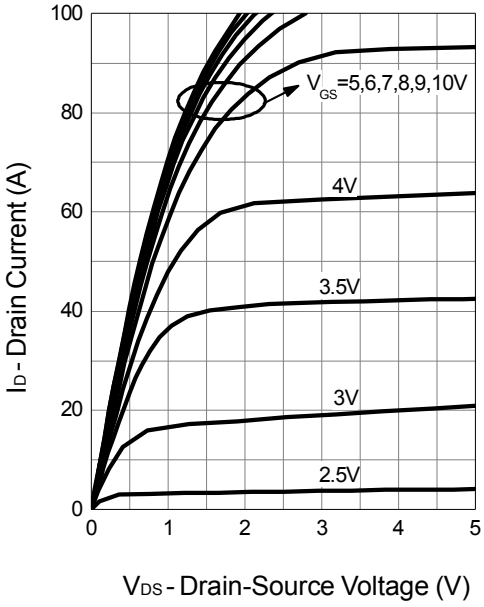


Thermal Transient Impedance

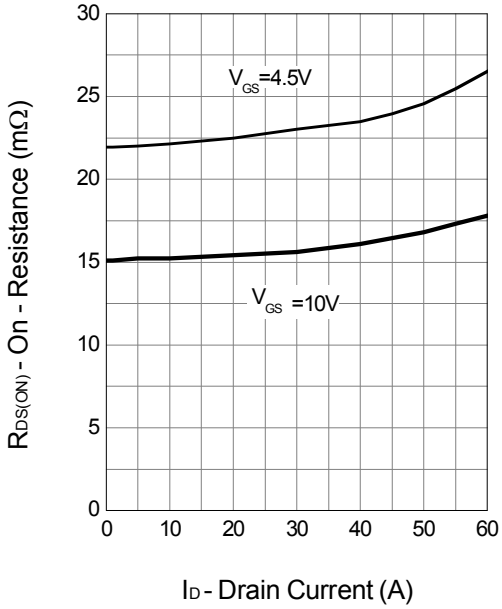


Typical Operating Characteristics (Cont.)

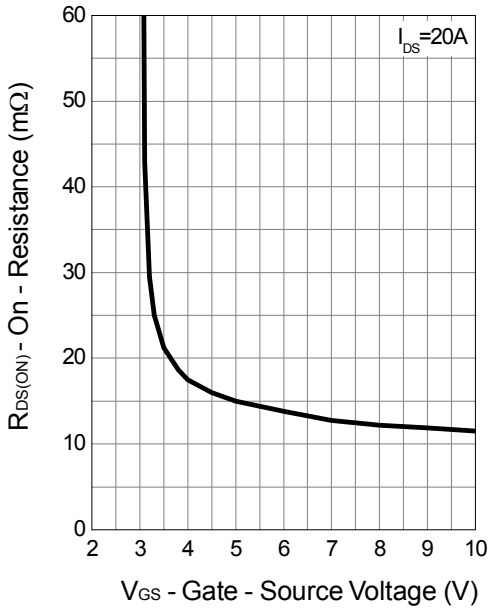
Output Characteristics



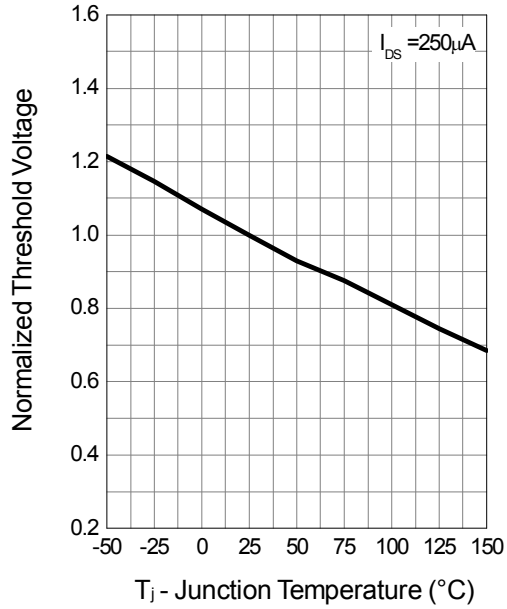
Drain-Source On Resistance



Gate-Source On Resistance

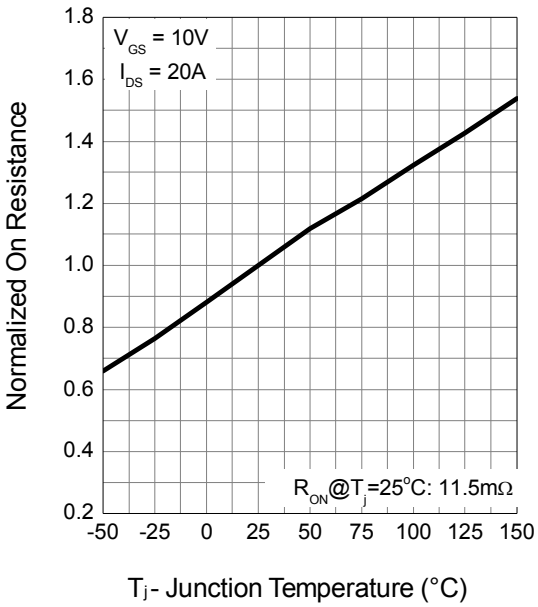


Gate Threshold Voltage

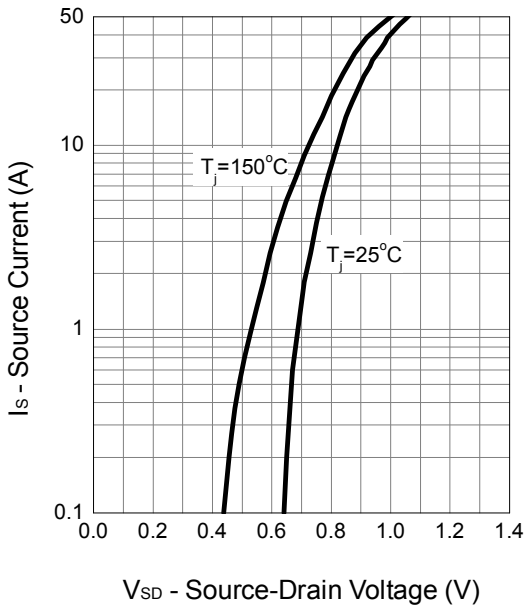


Typical Operating Characteristics (Cont.)

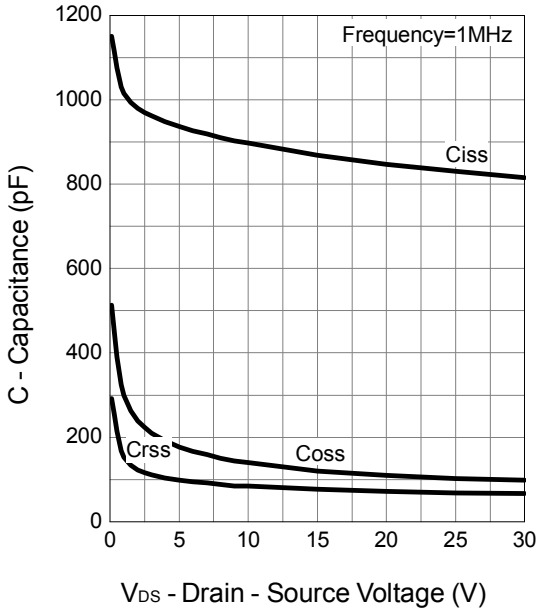
Drain-Source On Resistance



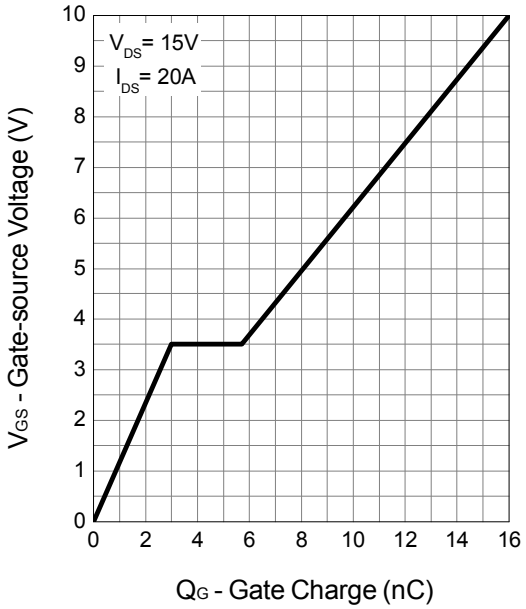
Source-Drain Diode Forward



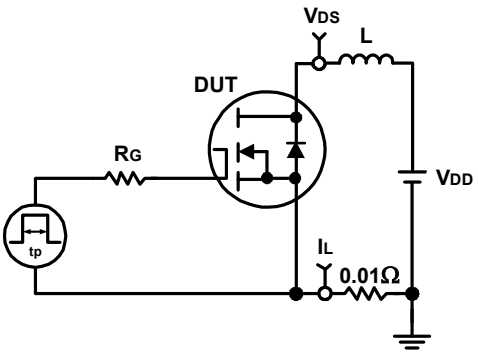
Capacitance

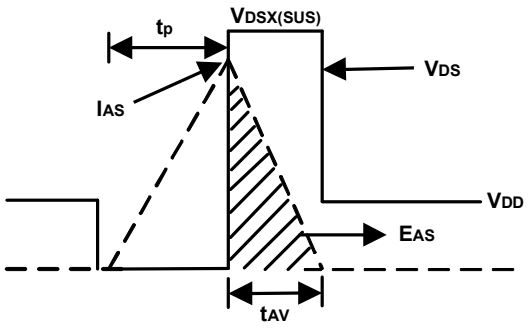


Gate Charge

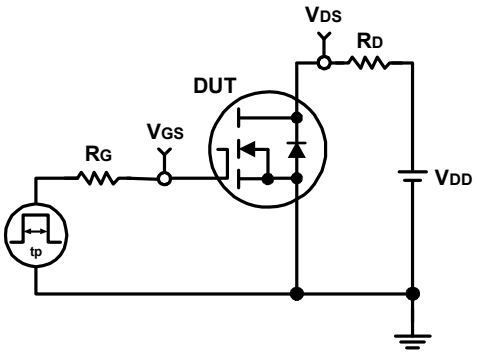


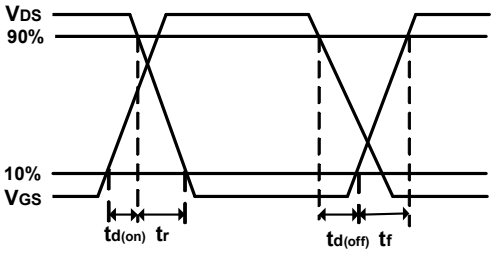
Avalanche Test Circuit and Waveforms





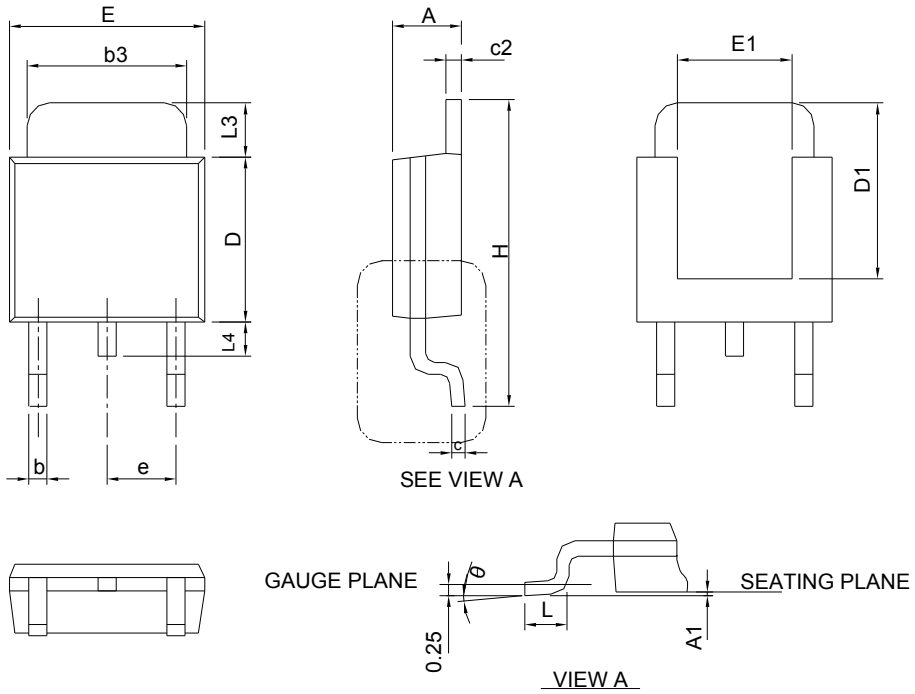
Switching Time Test Circuit and Waveforms





Package Information

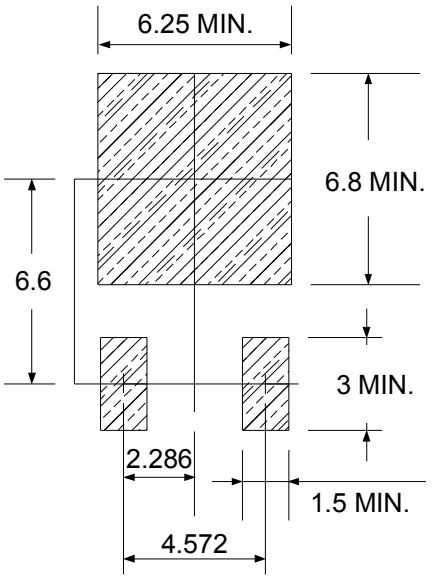
TO-252-2



SYMBOL	TO-252-2			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1	-	0.13	-	0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4	-	1.02	-	0.040
θ	0°	8°	0°	8°

Note : Follow JEDEC TO-252-2 .

RECOMMENDED LAND PATTERN



UNIT: mm